Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1-8. (**canceled**)

9. (**previously presented**) A method for fabricating a wire grid polarizer, comprising:

depositing a wire grid material on a substrate, wherein the wire grid material comprises a dielectric material sandwiched between two metallic materials, wherein the dielectric and metallic materials act in concert to suppress reflection of rejected polarization;

depositing a resist film on the wire grid material;

bringing a mold with a wire grid pattern in contact with the resist film and compressing the mold and resist film together so as to emboss the wire grid pattern in the resist film; and

transferring the wire grid pattern in the resist film to the wire grid material on the substrate by etching.

10. (**original**) The method of claim 9, wherein the metallic materials are selected from the group consisting of Al, Au, Cu, Ir, Mo, Ni, Os, Pt, Rh, and W.

11. (**original**) The method of claim 9, wherein the dielectric material is selected from the group consisting of Si, SiO_2, and GaAs.

12. (**original**) The method of claim 9, wherein the resist film comprises a thermoplastic polymer.

13. (**original**) The method of claim 12, further comprising heating the mold, the resist film and the substrate to a temperature above the glass transition temperature of the thermoplastic polymer prior to contacting the mold with the resist film.

14. (**original**) The method of claim 9, further comprising applying an anti-reflective coating on the substrate prior to depositing the wire grid material on the substrate.

15. (**previously presented**) The method of claim 9, wherein the substrate is made of a magneto-optical garnet material.

16-25. (**canceled**)

26. (**new**) A method of fabricating an integrated optical isolator, comprising:

forming a wire grid polarizer on a first and a second surface of a substrate made of a magneto-optical garnet material, the wire grid polarizer on the first surface being rotated at an angle relative to the wire grid polarizer on the second surface;

wherein forming the wire grid polarizer on the first and second surfaces of the substrate comprises depositing a wire grid material on the respective surface of the substrate, depositing a resist film on the wire grid material, bringing a mold with a wire grid pattern in contact with the resist film and compressing the mold and resist film together so as to emboss the wire grid pattern in the resist film, and transferring the wire grid pattern in the resist film to the wire grid material on the substrate by etching;

wherein the wire grid material deposited on at least one of the first and second surfaces of the substrate comprises a dielectric material sandwiched between two metallic materials, and wherein the dielectric and metallic materials act in concert to suppress reflection of rejected polarization.

27. (**new**) The method of claim 26, wherein the metallic materials are selected from the group consisting of Al, Au, Cu, Ir, Mo, Ni, Os, Pt, Rh, and W.

28. (**new**) The method of claim 26, wherein the dielectric material is selected from the group consisting of Si, SiO_2, and GaAs.

29. (**new**) The method of claim 26, wherein the resist film comprises a thermoplastic polymer.

30. (**new**) The method of claim 29, further comprising heating the mold, the resist film and the substrate to a temperature above the glass transition temperature of the thermoplastic polymer prior to contacting the mold with the resist film.

B4 Concl'd

31. (**new**) The method of claim 26, further comprising applying an anti-reflective coating on the substrate prior to depositing the wire grid material on the substrate.